

FP-BGA
Commercial Temp
Industrial Temp

128K x 8
1Mb Asynchronous SRAM

7, 8, 10, 12 ns
3.3 V V_{DD}
Center V_{DD} and V_{SS}

Features

- Fast access time: 7, 8, 10, 12 ns
- CMOS low power operation: 140/120/95/80 mA at minimum cycle time
- Single 3.3 V power supply
- All inputs and outputs are TTL-compatible
- Fully static operation
- Industrial Temperature Option: -40° to 85°C
- Package line up
 - U: 6 mm x 8 mm Fine Pitch Ball Grid Array package
 - GU: RoHS-compliant 6 mm x 8 mm Fine Pitch Ball Grid Array package

Description

The GS71108A is a high speed CMOS Static RAM organized as 131,072 words by 8 bits. Static design eliminates the need for external clocks or timing strobes. The GS 71108 operates on a single 3.3 V power supply and all inputs and outputs are TTL-compatible. The GS71108A is available in the 6 mm x 8 mm Fine Pitch BGA package.

Fine Pitch BGA 128K x 8-Bump Configuration

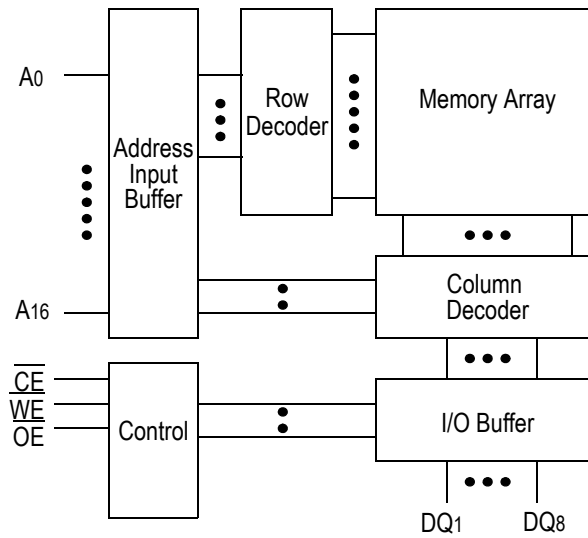
| | 1 | 2 | 3 | 4 | 5 | 6 |
|---|----------|------------------------|-----|-----|------------------------|----------|
| A | NC | $\overline{\text{OE}}$ | A2 | A6 | A7 | NC |
| B | DQ1 | NC | A1 | A5 | $\overline{\text{CE}}$ | DQ8 |
| C | DQ2 | NC | A0 | A4 | NC | DQ7 |
| D | V_{SS} | NC | NC | A3 | NC | V_{DD} |
| E | V_{DD} | NC | NC | NC | NC | V_{SS} |
| F | DQ3 | NC | A14 | A11 | DQ5 | DQ6 |
| G | DQ4 | NC | A15 | A12 | $\overline{\text{WE}}$ | A8 |
| H | NC | A10 | A16 | A13 | A9 | NC |

Package U
6 mm x 8 mm, 0.75 mm Bump Pitch
Top View

Pin Descriptions

| Symbol | Description |
|----------------------------------|---------------------|
| A ₀ –A ₁₆ | Address input |
| DQ ₁ –DQ ₈ | Data input/output |
| $\overline{\text{CE}}$ | Chip enable input |
| $\overline{\text{WE}}$ | Write enable input |
| $\overline{\text{OE}}$ | Output enable input |
| V_{DD} | +3.3 V power supply |
| V_{SS} | Ground |
| NC | No connect |

Block Diagram



Truth Table

| \overline{CE} | \overline{OE} | \overline{WE} | DQ1 to DQ8 | V_{DD} Current |
|-----------------|-----------------|-----------------|--------------|------------------|
| H | X | X | Not Selected | ISB1, ISB2 |
| L | L | H | Read | IDD |
| L | X | L | Write | |
| L | H | H | High Z | |

Note:
X: "H" or "L"

Absolute Maximum Ratings

| Parameter | Symbol | Rating | Unit |
|-----------------------------|------------------|--|------|
| Supply Voltage | V _{DD} | -0.5 to +4.6 | V |
| Input Voltage | V _{IN} | -0.5 to V _{DD} +0.5 (≤ 4.6 V max.) | V |
| Output Voltage | V _{OUT} | -0.5 to V _{DD} +0.5 (≤ 4.6 V max.) | V |
| Allowable power dissipation | PD | 0.7 | W |
| Storage temperature | T _{STG} | -55 to 150 | °C |

Note:

Permanent device damage may occur if Absolute Maximum Ratings are exceeded. Functional operation shall be restricted to Recommended Operating Conditions. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

Recommended Operating Conditions

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-----------------|------|-----|----------------------|------|
| Supply Voltage for -7/-8/-10/-12 | V _{DD} | 3.0 | 3.3 | 3.6 | V |
| Input High Voltage | V _{IH} | 2.0 | — | V _{DD} +0.3 | V |
| Input Low Voltage | V _{IL} | -0.3 | — | 0.8 | V |
| Ambient Temperature, Commercial Range | T _{Ac} | 0 | — | 70 | °C |
| Ambient Temperature, Industrial Range | T _{AI} | -40 | — | 85 | °C |

Notes:

1. Input overshoot voltage should be less than V_{DD} +2 V and not exceed 20 ns.
2. Input undershoot voltage should be greater than -2 V and not exceed 20 ns.

Capacitance

| Parameter | Symbol | Test Condition | Max | Unit |
|--------------------|------------------|------------------------|-----|------|
| Input Capacitance | C _{IN} | V _{IN} = 0 V | 5 | pF |
| Output Capacitance | C _{OUT} | V _{OUT} = 0 V | 7 | pF |

Notes:

1. Tested at T_A = 25°C, f = 1 MHz
2. These parameters are sampled and are not 100% tested.

DC I/O Pin Characteristics

| Parameter | Symbol | Test Conditions | Min | Max |
|------------------------|-----------------|--|-------|-------|
| Input Leakage Current | I _{IL} | V _{IN} = 0 to V _{DD} | -1 uA | 1 uA |
| Output Leakage Current | I _{LO} | Output High Z V _{OUT} = 0 to V _{DD} | -1 uA | 1 uA |
| Output High Voltage | V _{OH} | I _{OH} = -4 mA | 2.4 | — |
| Output Low Voltage | V _{OL} | I _{LO} = +4 mA | — | 0.4 V |

Power Supply Currents

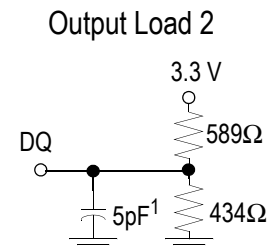
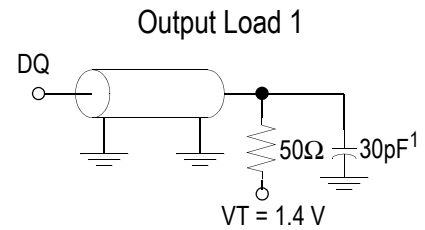
| Parameter | Symbol | Test Conditions | 0 to 70°C | | | | -40 to 85°C | | | |
|--------------------------|------------------|--|-----------|--------|-------|-------|-------------|--------|--------|-------|
| | | | 7 ns | 8 ns | 10 ns | 12 ns | 7 ns | 8 ns | 10 ns | 12 ns |
| Operating Supply Current | I _{DD} | $\overline{CE} \leq V_{IL}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time I _{OUT} = 0 mA | 140 mA | 120 mA | 95 mA | 80 mA | 145 mA | 125 mA | 100 mA | 85 mA |
| Standby Current | I _{SB1} | $\overline{CE} \geq V_{IH}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time | 25 mA | 20 mA | 20 mA | 15 mA | 30 mA | 25 mA | 25 mA | 20 mA |
| Standby Current | I _{SB2} | $\overline{CE} \geq V_{DD} - 0.2 V$ All other inputs $\geq V_{DD} - 0.2 V$ or $\leq 0.2 V$ | 2 mA | | | | 5 mA | | | |

AC Test Conditions

| Parameter | Conditions |
|------------------------|-------------------------|
| Input high level | $V_{IH} = 2.4\text{ V}$ |
| Input low level | $V_{IL} = 0.4\text{ V}$ |
| Input rise time | $t_r = 1\text{ V/ns}$ |
| Input fall time | $t_f = 1\text{ V/ns}$ |
| Input reference level | 1.4 V |
| Output reference level | 1.4 V |
| Output load | Fig. 1 & 2 |

Notes:

1. Include scope and jig capacitance.
2. Test conditions as specified with output loading as shown in **Fig. 1** unless otherwise noted.
3. Output load 2 for t_{LZ} , t_{HZ} , t_{OLZ} and t_{OHZ}



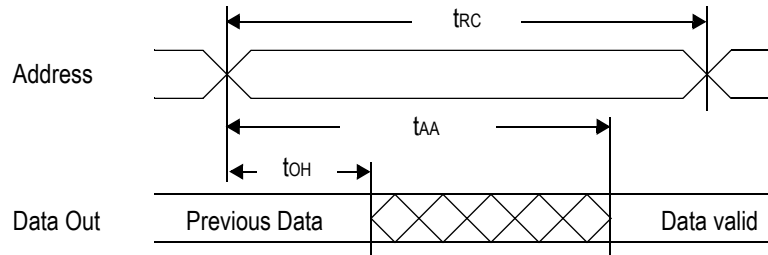
AC Characteristics

Read Cycle

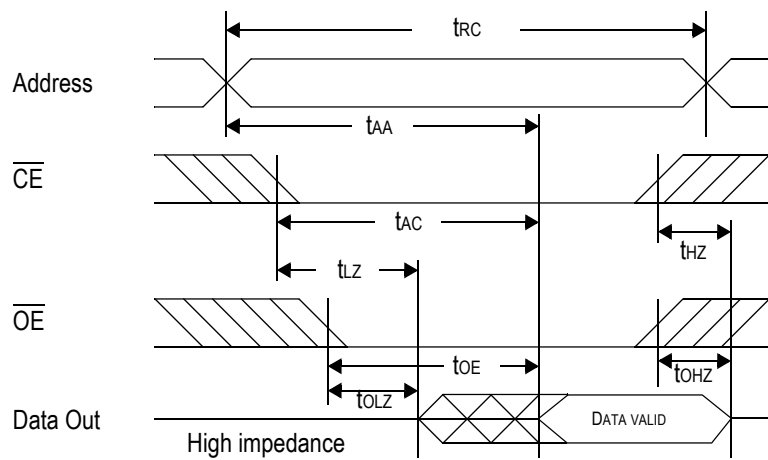
| Parameter | Symbol | -7 | | -8 | | -10 | | -12 | | Unit |
|--|-------------|-----|-----|-----|-----|-----|-----|-----|-----|------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| Read cycle time | t_{RC} | 7 | — | 8 | — | 10 | — | 12 | — | ns |
| Address access time | t_{AA} | — | 7 | — | 8 | — | 10 | — | 12 | ns |
| Chip enable access time (\overline{CE}) | t_{AC} | — | 7 | — | 8 | — | 10 | — | 12 | ns |
| Output enable to output valid (\overline{OE}) | t_{OE} | — | 3 | — | 3.5 | — | 4 | — | 5 | ns |
| Output hold from address change | t_{OH} | 3 | — | 3 | — | 3 | — | 3 | — | ns |
| Chip enable to output in low Z (\overline{CE}) | t_{LZ}^* | 3 | — | 3 | — | 3 | — | 3 | — | ns |
| Output enable to output in low Z (\overline{OE}) | t_{OLZ}^* | 0 | — | 0 | — | 0 | — | 0 | — | ns |
| Chip disable to output in High Z (\overline{CE}) | t_{HZ}^* | — | 3.5 | — | 4 | — | 5 | — | 6 | ns |
| Output disable to output in High Z (\overline{OE}) | t_{OHZ}^* | — | 3 | — | 3.5 | — | 4 | — | 5 | ns |

* These parameters are sampled and are not 100% tested

Read Cycle 1: $\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$



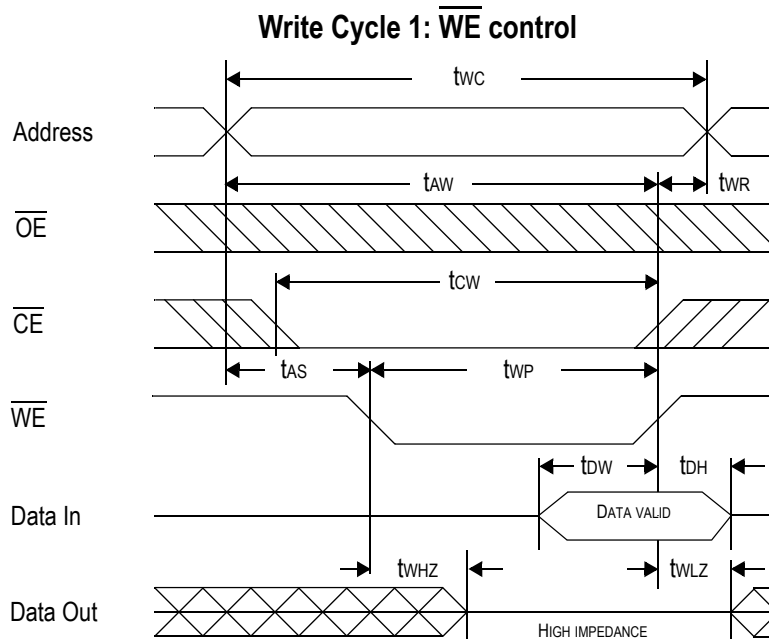
Read Cycle 2: $\overline{WE} = V_{IH}$



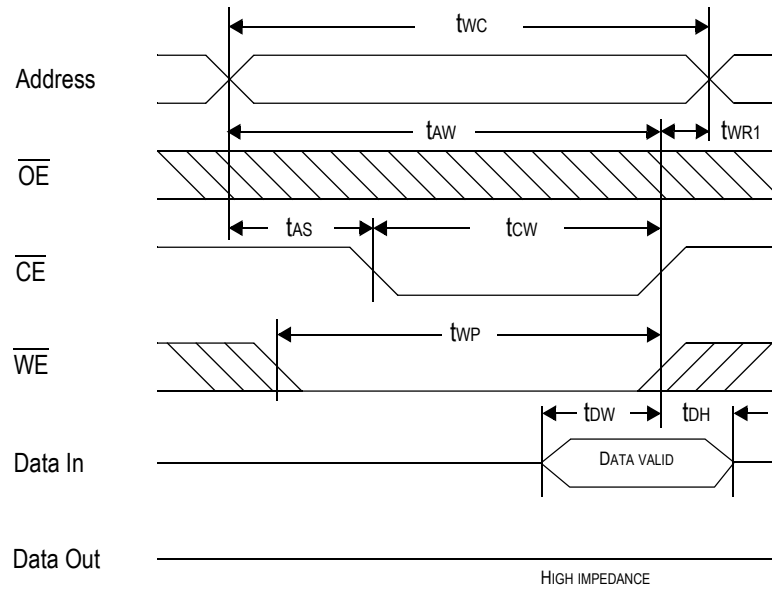
Write Cycle

| Parameter | Symbol | -7 | | -8 | | -10 | | -12 | | Unit |
|---|--------|-----|-----|-----|-----|-----|-----|-----|-----|------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| Write cycle time | tWC | 7 | — | 8 | — | 10 | — | 12 | — | ns |
| Address valid to end of write | tAW | 5 | — | 5.5 | — | 7 | — | 8 | — | ns |
| Chip enable to end of write | tCW | 5 | — | 5.5 | — | 7 | — | 8 | — | ns |
| Data set up time | tDW | 3 | — | 4 | — | 5 | — | 6 | — | ns |
| Data hold time | tDH | 0 | — | 0 | — | 0 | — | 0 | — | ns |
| Write pulse width | tWP | 5 | — | 5.5 | — | 7 | — | 8 | — | ns |
| Address set up time | tAS | 0 | — | 0 | — | 0 | — | 0 | — | ns |
| Write recovery time (\overline{WE}) | tWR | 0 | — | 0 | — | 0 | — | 0 | — | ns |
| Write recovery time (\overline{CE}) | tWR1 | 0 | — | 0 | — | 0 | — | 0 | — | ns |
| Output Low Z from end of write | tWLZ* | 3 | — | 3 | — | 3 | — | 3 | — | ns |
| Write to output in High Z | tWHZ* | — | 3 | — | 3.5 | — | 4 | — | 5 | ns |

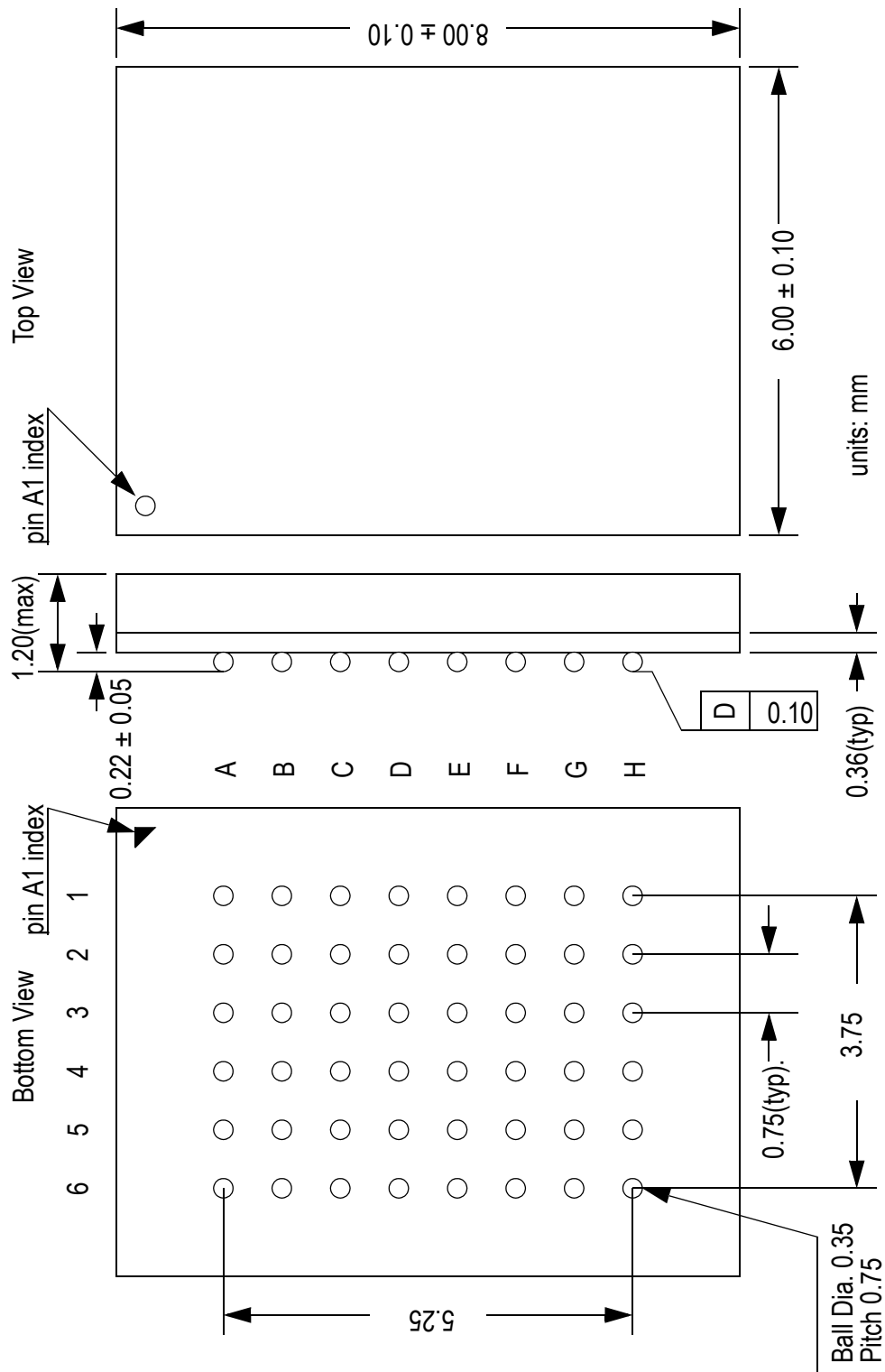
* These parameters are sampled and are not 100% tested



Write Cycle 2: \overline{CE} control



6 mm x 8 mm Fine Pitch BGA



Ordering Information

| Part Number* | Package | Access Time | Temp. Range |
|----------------|---|-------------|-------------|
| GS71108AU-7 | 6 mm x 8 mm Fine Pitch BGA | 7 ns | Commercial |
| GS71108AU-8 | 6 mm x 8 mm Fine Pitch BGA | 8 ns | Commercial |
| GS71108AU-10 | 6 mm x 8 mm Fine Pitch BGA | 10 ns | Commercial |
| GS71108AU-12 | 6 mm x 8 mm Fine Pitch BGA | 12 ns | Commercial |
| GS71108AU-7I | 6 mm x 8 mm Fine Pitch BGA | 7 ns | Industrial |
| GS71108AU-8I | 6 mm x 8 mm Fine Pitch BGA | 8 ns | Industrial |
| GS71108AU-10I | 6 mm x 8 mm Fine Pitch BGA | 10 ns | Industrial |
| GS71108AU-12I | 6 mm x 8 mm Fine Pitch BGA | 12 ns | Industrial |
| GS71108AGU-7 | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 7 ns | Commercial |
| GS71108AGU-8 | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 8 ns | Commercial |
| GS71108AGU-10 | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 10 ns | Commercial |
| GS71108AGU-12 | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 12 ns | Commercial |
| GS71108AGU-7I | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 7 ns | Industrial |
| GS71108AGU-8I | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 8 ns | Industrial |
| GS71108AGU-10I | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 10 ns | Industrial |
| GS71108AGU-12I | RoHS-compliant 6 mm x 8 mm Fine Pitch BGA | 12 ns | Industrial |

Note:

Customers requiring delivery in Tape and Reel should add the character "T" to the end of the part number. For example: GS71108AU-8T.

1Mb Asynchronous Datasheet Revision History

| Rev. Code: Old; New | Types of Changes Format or Content | Page #/Revisions/Reason |
|----------------------------|---------------------------------------|--|
| 71108A_r1 | | • Creation of new datasheet |
| 71108A_r1; 71108A_r1_01 | Content | • Added 6 ns speed bin to entire document |
| 71108A_r1_01; 71108A_r1_02 | Content | • Updated all power numbers • Changed 6 mm x 10 mm package designator from U to X |
| 71108A_r1_02; 71108A_r1_03 | Content | • Updated Recommended Operating Conditions table on page 3 • Updated Power Supply Currents table • Changed FPBGA package from 6 x 10 to 6 x 8 (package U) |
| 71108A_r1_03; 71108A_r1_04 | Content | • Removed 6 ns speed bin from entire document • Added 7 ns speed bin to entire document |
| 71108A_r1_04; 71108A_r1_05 | Content | • Added missing 300 mil SOJ mechanical drawing |
| 71108A_r1_05; 71108A_r1_06 | Content | • Updated format • Added RoHS-compliant information for TSOP-II package |
| 71108A_r1_06; 71108A_r1_07 | Content | • Added RoHS-compliant information for FP-BGA package |
| 71108A_r1_07; 71108A_r1_08 | Content | • Added RoHS-compliant 400 mil, 32-pin SOJ |
| 71108A_r1_08; 71108A_r1_09 | Content | • Updated to MP in ordering information table |
| 71108A_r1_09; 71108A_r1_10 | Content | • Removed Status column from Ordering Information Table • Removed SOJ package reference from entire document • (Rev1.10a: Removed TSOP-II references due to EOL (EOL_091016111-CY) |

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